

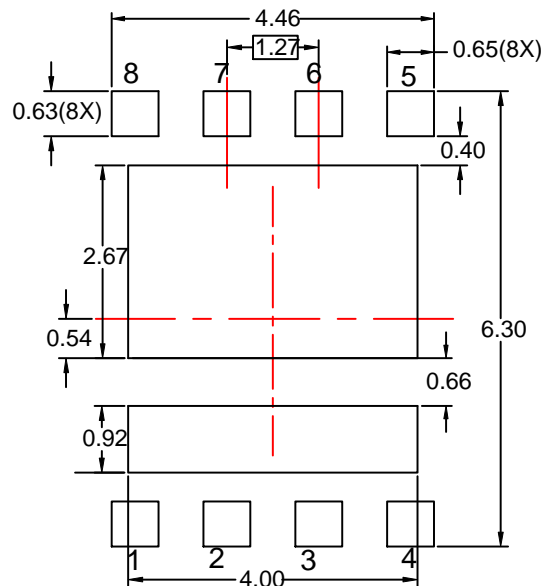
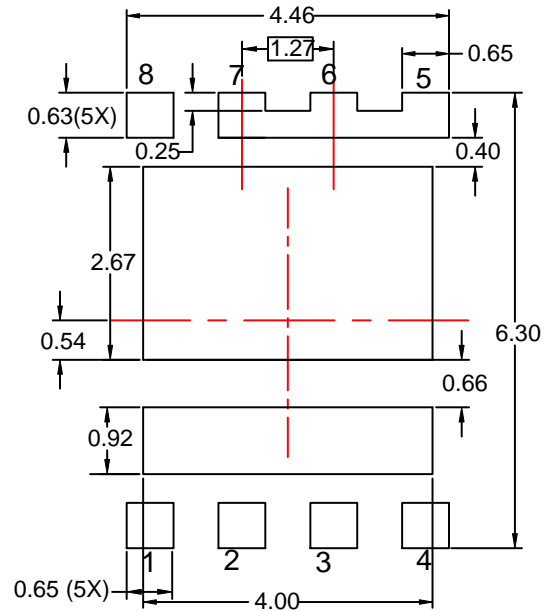
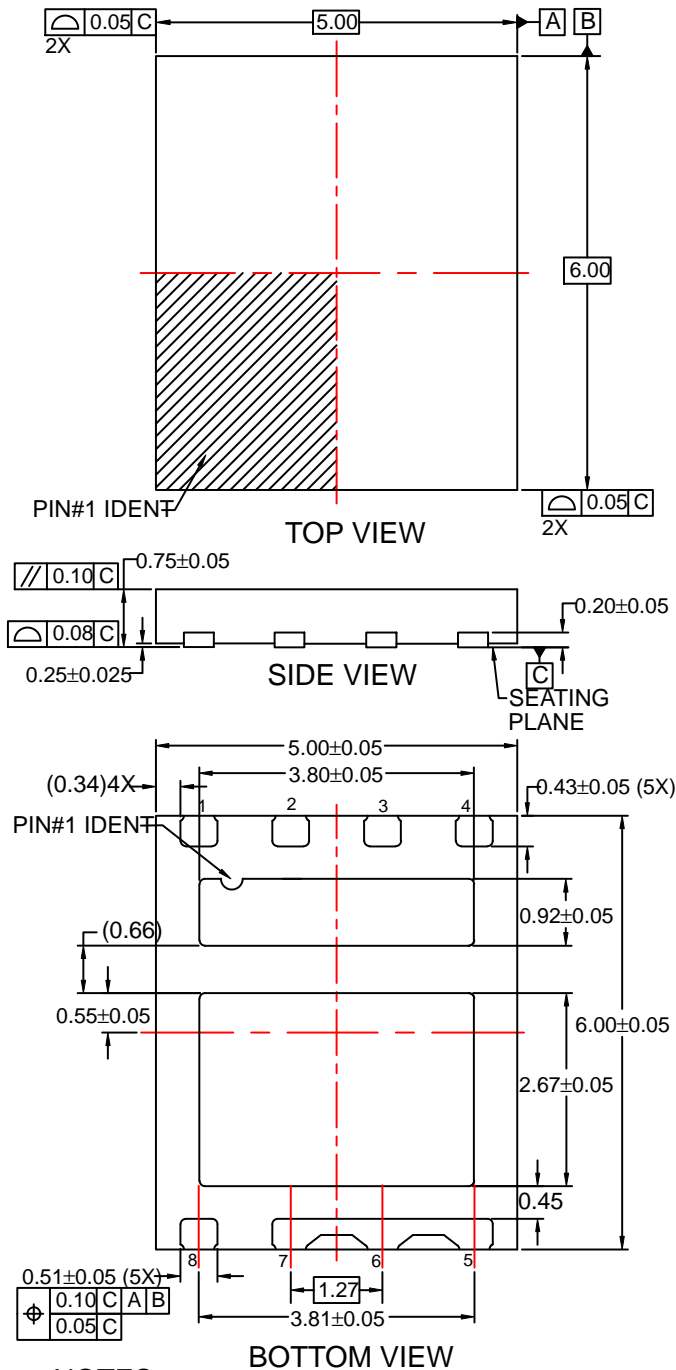
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**DFN8 5x6, 1.27P**  
CASE 506DR  
ISSUE O

DATE 31 JUL 2016



- NOTES:**  
A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.  
B. DIMENSIONS ARE IN MILLIMETERS.  
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>DFN8 5X6, 1.27P</b>	<b>PAGE 1 OF 2</b>

